

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Solder Wire	Tin alloy	Tin (Sn)	7440-31-5	0.01141	10.0	0.17187
	Silver alloy	Silver (Ag)	7440-22-4	0.00228	2.0	0.03437
	Lead alloy	Lead (Pb)	7439-92-1	0.10044	88.0	1.51248
<b>Subtotal</b>				<b>0.11413</b>	<b>100</b>	<b>1.71872</b>
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.57035	100.0	8.58835
Die	Doped silicon	Silicon (Si)	7440-21-3	0.16071	100.0	2.42
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.00976	0.03	0.14694
	Pure metal layer	Zinc (Zn)	7440-66-6	0.00651	0.02	0.09796
	Pure metal layer	Tin (Sn)	7440-31-5	0.00976	0.03	0.14694
	Pure metal layer	Iron (Fe)	7439-89-6	0.03578	0.11	0.53877
	Pure metal layer	Copper (Cu)	7440-50-8	32.46494	99.81	488.8594
<b>Subtotal</b>				<b>32.52675</b>	<b>100</b>	<b>489.79001</b>
Post-plating	Pure metal	Tin (Sn)	7440-31-5	0.32209	100.0	4.85
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	5.30448	8.0	79.8752
	Filler	Silica fused	60676-86-0	53.70784	81.0	808.7364
	Metal hydroxide	Metal hydroxide		0.46414	0.7	6.98908
	Carbon Black	Carbon black	1333-86-4	0.19892	0.3	2.99532
	Polymer	Epoxy resin system		6.6306	10.0	99.844
<b>Subtotal</b>				<b>66.30598</b>	<b>100</b>	<b>998.44</b>
<b>Total</b>				<b>100.00001</b>	<b>100</b>	<b>1505.80708</b>

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